

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,858,904 B2
APPLICATION NO. : 09/994903
DATED : February 22, 2005
INVENTOR(S) : Derraa et al.

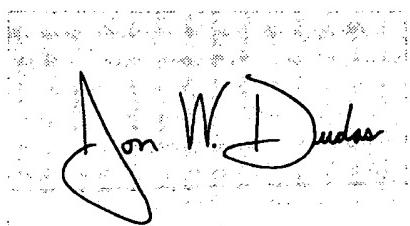
Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

At Column 8, Line 2, in Claim 10, after "region," please add -- wherein a substantial portion of the titanium silicide is interspersed in the titanium before the conductive contact layer is deposited on the upper surface of the silicon substrate over the junction region, --

Signed and Sealed this

Twenty-ninth Day of August, 2006



JON W. DUDAS
Director of the United States Patent and Trademark Office